Materials Declaration

Package	SOIC_W
Body Size	300 mil
LeadCount	20
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.0	3.22 E-01	564874
Resin	10.9	4.04 E-02	70771
Sb2O3	1.5	5.55 E-03	9739
Brominated Resin	0.6	2.22 E-03	3895
Subtotal		3.70 E-01	649279

Item	PPM
Pb	Not Detected
Cd	Not Detected
Hg	Not Detected
Cr+6	Not Detected
PBB	Not Detected
PBDE	Not Detected

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.65 E-01	289609
Fe	2.35	3.98 E-03	6980
Zn	0.12	2.03 E-04	356
P	0.03	5.10 E-05	89
Subtotal		1.69 E-01	297035

Item	PPM
Pb	Not Detected
Cd	Not Detected
Hg	Not Detected
Cr+6	Not Detected
PBB	Not Detected
PBDE	Not Detected

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	2.01 E-03	3530

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.70 E-03	6480

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	7.67 E-04	1345

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.00 E-02	35142

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	3.07 E-03	5391
Resin	20	8.20 E-04	1438
Aromatic Amine	5	2.05 E-04	360
Subtotal		4.10 E-03	7189

Package Totals

Weight (g)	PPM
5.70 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no lial
any inaccuracy of such information.

ADI Proprietary

Molding Compound

Method
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3060A & 7196A. UV-VIS.
EPA Method 3550/3540C. GC/MS.
EPA Method 3550/3540C. GC/MS.

Die Attach Paste

Method
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3060A & 7196A. UV-VIS.
EPA Method 3550/3540C. GC/MS.
EPA Method 3550/3540C. GC/MS.

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Materials Declaration

Package	SOIC_W
Body Size	300 mil
LeadCount	20
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	3.22 E-01	564573
Resin	14.2	4.04 E-02	70734
Sb2O3	0.5	5.55 E-03	9733
Brominated Resin	0.35	2.22 E-03	3893
Subtotal		3.70 E-01	648933

Item	PPM
Pb	Not Detected
Cd	Not Detected
Hg	Not Detected
Cr+6	Not Detected
PBB	Not Detected
PBDE	Not Detected

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	1.65 E-01	289455
Fe	2.35	3.98 E-03	6976
Zn	0.12	2.03 E-04	356
P	0.03	5.10 E-05	89
Subtotal		1.69 E-01	296876

Item	PPM
Pb	Not Detected
Cd	Not Detected
Hg	Not Detected
Cr+6	Not Detected
PBB	Not Detected
PBDE	Not Detected

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	2.01 E-03	3528

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	3.40 E-03	5958
Pb	15	6.00 E-04	1052
Subtotal		4.00 E-03	7010

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	7.67 E-04	1344

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	2.00 E-02	35123

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	3.07 E-03	5388
Resin	20	8.20 E-04	1437
Aromatic Amine	5	2.05 E-04	359
Subtotal		4.10 E-03	7185

Package Totals

Weight (g)	PPM
5.71 E-01	1000000

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any inaccuracy of such information.

ADI Proprietary

Molding Compound

Method
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3060A & 7196A. UV-VIS.
EPA Method 3550/3540C. GC/MS.
EPA Method 3550/3540C. GC/MS.

Die Attach Paste

Method
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3051/3052. ICP-OES
EPA Method 3060A & 7196A. UV-VIS.
EPA Method 3550/3540C. GC/MS.
EPA Method 3550/3540C. GC/MS.

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